

Author	Review article	Citations	Journal	Year published	DOI or weblink
Kanarik, K. J.; Lill, T.; Hudson, E. A.; Sriraman, S.; Tan, S.; Marks, J.; Vahedi, V.; Gottscho, R. A.	Overview of atomic layer etching in the semiconductor industry	265	J. Vac. Sci. Technol. A	2015	<a href="https://doi.org/10.1116/1.4913379">https://doi.org/10.1116/1.4913379</a>
Carver, Colin T.; Plombon, John J.; Romero, Patricio E.; Suri, Satyarth; Tronic, Tristan A.; Turkot., Robert B.	Atomic Layer Etching at the Tipping Point: An Overview	90	J. Solid State Sci. Technol.	2015	<a href="https://doi.org/10.1149/2.0021506jss">https://doi.org/10.1149/2.0021506jss</a>
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Oehrlein, G. S.; Metzler, D.; Li, C.	Atomic Layer Etching at the Tipping Point: An Overview	131	J. Solid State Sci. Technol.	2015	<a href="https://doi.org/10.1149/2.0061506jss">https://doi.org/10.1149/2.0061506jss</a>
Fang, C.; Cao, Y. Q.; Wu, D.; Li, A. D.	Thermal atomic layer etching: Mechanism, materials and prospects	14	Prog. Nat	2018	<a href="https://doi.org/10.1016/j.pnsc.2018.11.003">https://doi.org/10.1016/j.pnsc.2018.11.003</a>
Sang, X.; Chang, J. P.	Physical and chemical effects in directional atomic layer etching	5	J. Phys. D	2020	<a href="https://doi.org/10.1088/1361-6463/ab6d94">https://doi.org/10.1088/1361-6463/ab6d94</a>
Kim, D. S.; Kim, J. E.; Gill, Y. J.; Jang, Y. J.; Kim, Y. E.; Kim, K. N.; Yeom, G. Y.; Kim, D. W.	Anisotropic/Isotropic Atomic Layer Etching of Metals	0	Appl. Sci. Conv. Technol.	2020	<a href="https://doi.org/10.5757/ASCT.2020.29.3.041">https://doi.org/10.5757/ASCT.2020.29.3.041</a>
George, S. M.	Mechanisms of Thermal Atomic Layer Etching	30	Acc. Chem. Res.	2020	<a href="https://doi.org/10.1021/acs.accounts.0c00084">https://doi.org/10.1021/acs.accounts.0c00084</a>
Gasvoda, R. J.; Zhang, Z. H.; Wang, S.; Hudson, E. A.; Agarwal, S.	Etch selectivity during plasma-assisted etching of SiO <sub>2</sub> and SiN <sub>x</sub> : Transitioning from reactive ion etching to atomic layer etching	5	J. Vac. Sci. Technol. A	2020	<a href="https://doi.org/10.1116/6.0000395">https://doi.org/10.1116/6.0000395</a>
Fischer, A.; Routzahn, A.; George, S. M.; Lill, T.	Thermal atomic layer etching: A review	5	J. Vac. Sci. Technol. A	2021	<a href="https://doi.org/10.1116/6.0000894">https://doi.org/10.1116/6.0000894</a>
Tsai, Yuanlu; Li, Zhiteng; Hu, Shaojie	Recent Progress in Atomic Layer Technology in Spintronics: Mechanisms, Materials and Prospects	0	Nanomaterials	2022	<a href="https://doi.org/10.3390/nano12040661">https://doi.org/10.3390/nano12040661</a>